Α	L		G CIRCUIT FOR CMOS SPADS 1 Kramnik		Ą
	SHEET	CONTENTS	Changelog (Rev. 2):		
	1	TABLE OF CONTENTS	- Added quench/reset slew rate adjustment - Switched comp. latch delay line to an adjustable starved inverter		
	2	OUTPUT DRIVER	- Added SPAD anode test point for scope probe		В
В	3	OUTPUT DRIVER BIASING	- Added bias current sensing connector to external 50R term. - Switched to higher precision output buffer biasing w/. matched FET cascoded mirrors - Added STM32 MCU and DACs to replace all bias adjustments		
	4	AVALANCHE DETECTOR	- Switched control of V_A-V_Q to DAC instead of resistor divider - Added USB-powered SMPS for all power supply rails, no more exteral supply required		
	5	HOLDOFF ONE-SHOT	Changelog (Rev. 3):	C	_
	6	HIGH-SPEED USER IO GLUE LOGIC	- Adjusted position of USB connector to be 1.6mm off edge of PCB - Added 90-degree triple-LED inducator next to USB port		С
С	7	CONTROL DACS	- Changed SMA package to have thinner signal pad for better impedance matching - Added TVS diode to SPAD output as an ESD precaution		
	8				
	9	- Switched boost inductor to be larger to prevent saturation and improve max. conversion ra Switched boost inductor to be larger to prevent saturation and improve max. conversion ra - Removed slew and delay generators, since we can trap ion and operate APDs as-is, or place a slowdown cap across load resistor of level shifter		-	_
	10	POSITIVE DC/DC SMPS	- Switched to faster HFA3134/HFA3135 matched BJTs for output buffer, and added extra cascode stacks to prevent breakdown		
D	11	NEGATIVE DC/DC SMPS	- Redesigned one-shot for lower juter, and added option for digital one-shot dailing wico		D
	12	LINEAR POSTREGULATORS			
					_
	Layout Notes: Max. unterminated length for t rise = 1ns is ~1in.		TABLE OF CONTENTS		
E	IMPEDANCE CALCULATIONS:		TITLE: aqc-rev3	RLE LOGO	Ε
	(T = 1oz/ft^2, H = 9.58mil, E 8mil = 52.3 Ohm SE 9mil = 50.3 Ohm SE	Ref. 4PCB 4-Layer Stackup Specifications	1 of 1	REV: 3.0	
	10mil = 48.5 Ohm SE		Date: 7/8/18 5:34 PM Sheet: 1/2	12	





















